

Fig. 1

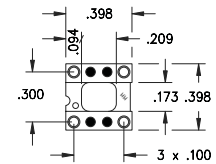


Fig. 2

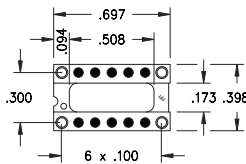


Fig. 3

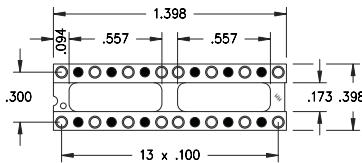
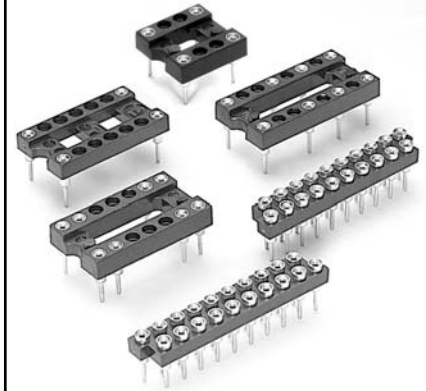


Fig. 4

○ = Loaded Position ● = Empty Position

- Relay sockets accept devices with I/O pins on .100" grid.
- Additional Relay DIP socket patterns are available on Page 86.1.
- Zig-Zag strip sockets are suitable for IC's and memory chips with staggered double row patterns.
- Series 110 and 410 use MM #1001 receptacles. See page 134 for details.
- Receptacles use Hi-Rel, 4 finger #30 BeCu contact rated at 3 amps. See page 208 for details.
- Insulators are high temp. thermoplastic.



Selectively Loaded Sockets For Dual-In-Line Relays

	No. of pins	Ordering Information
Fig. 1	6	110-XX-210-10-001000
Fig. 2	4	110-XX-308-10-001000
Fig. 3	4	110-XX-314-10-001000
Fig. 4	16	110-XX-328-10-001000

Staggered (Zig-Zag) Strip Sockets

Dim 'A'	No. of pins	Insulator Body	Ordering Information
0.747	14	Left, Stackable	410-93-214-10-001000
0.747	14	Right, Stackable	410-93-214-10-002000
0.847	16	Left, Stackable	410-93-216-10-001000
0.847	16	Right, Stackable	410-93-216-10-002000
1.047	20	Left, Stackable	410-93-220-10-001000
1.047	20	Right, Stackable	410-93-220-10-002000
1.247	24	Left, Stackable	410-93-224-10-001000
1.247	24	Right, Stackable	410-93-224-10-002000
1.447	28	Left, Stackable	410-93-228-10-001000
1.447	28	Right, Stackable	410-93-228-10-002000



XX= Plating Code
See Below

For RoHS compliance
select ◇ plating code.

SPECIFY PLATING CODE XX=	13◇	93	43◇
Sleeve (Pin)	10μ" Au	200μ" Sn/Pb	200μ" Sn
Contact (Clip)	30μ" Au	30μ" Au	30μ" Au